Product / Package Information	
Package	LGA_CAV
Body Size (mm)	3.76 X 4.72 X 1.0
Ball Count	9
Terminal Finish	Gold

Environmental Information	
RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Lid/Shield

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Stainless steel	Iron	7439-89-6	9.64 E-03	68.84	688402	32.53	325288
Stainless steel	Chromium	7440-47-3	2.42 E-03	17.31	173057	8.18	81774
Stainless steel	Nickel	7440-02-0	1.08 E-03	7.74	77445	3.66	36595
Stainless steel	Manganese	7439-96-5	1.70 E-04	1.21	12143	0.57	5738
Stainless steel	Silicon	7440-21-3	6.96 E-05	0.50	4972	0.23	2349
Stainless steel	Carbon	7440-44-0	6.56 E-06	0.05	468	0.02	221
Stainless steel	Phosphorus	7723-14-0	3.08 E-06	0.02	220	0.01	104
Stainless steel	Sulfur	7704-34-9	2.68 E-07	0.002	19	0.001	9
Tin & its alloys	Tin	7440-31-5	6.06 E-04	4.33	43274	2.04	20448
Subtotal			1.40 E-02	100.0	1000000	38.87	388723

Laminate

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Composite	Fibrous glass-wool						
Composite	Bis(3-ethyl-5-methyl-4-maleimidophenyl)methane						
Composite	Triazine						
Composite	Phenolic Polymer Resin						
Composite	Aluminium hydroxide						
	Laminate Subtotal	Proprietary	3.73 E-03	40.86	408633	12.59	125894
Other organic materials	Cured resin						
Other inorganic materials	Barium sulfate						
Other inorganic materials	Talc						
Other organic materials	Copper phthalocyanine blue						
Other inorganic materials	Silicon dioxide						
Other inorganic materials	Aluminium compounds						
	Solder Mask Subtotal	Proprietary	1.56 E-03	17.09	170903	5.27	52653
Copper & its alloys	Copper	7440-50-8	2.79 E-03	30.57	305653	9.42	94168
Nickel & its alloys	Nickel	7440-02-0	8.70 E-04	9.53	95311	2.94	29364
Precious Metals	Gold	7440-57-5	1.78 E-04	1.95	19500	0.60	6008
Subtotal			9.13 E-03	100.00	1000000	47.64	476425

Solder Land

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	4.50 E-04	73.68	736842	1.09	10877
Nickel & its alloys	Nickel	7440-02-0	1.20 E-04	21.05	210526	0.31	3108
Precious Metals	Gold	7440-57-5	3.00 E-05	5.26	52632	0.08	777
Subtotal			6.00 E-04	100.00	1000000	1.48	14762

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.90 E-05	99	990000	0.27	2665
Precious metals	Palladium	7440-05-3	1.00 E-06	1	10000	0.00	27
Subtotal			1.00 E-04	100	1000000	0.27	2692

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	4.20 E-03	100	1000000	6.60	66041

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	9.33 E-04	77.71	734000	2.48	24836
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	3.73 E-05	3.11	183500	0.62	6209
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	3.73 E-05	3.11	27500	0.09	930
Other organic materials	Butyrolactone, gamma-	96-48-0	3.73 E-05	3.11	27500	0.09	930
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	3.73 E-05	3.11	27500	0.09	930
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.73 E-05	3.11	27500	0.09	930
Other organic materials	Organosilane	TS ref# 10001	3.73 E-05	3.11	27500	0.09	930
Other inorganic materials	Copper(II) oxide	1317-38-0	3.73 E-05	3.11	27500	0.09	930
Other organic materials	Epoxy resin modifier	TS ref# 10038	6.24 E-06	0.52	27500	0.09	930
Subtotal			1.20 E-03	100.00	1000000	3.38	33836

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Polydimethylsiloxane	Proprietary	2.00 E-04	100	1000000	0.88	8780

Lid/ Shield Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.50 E-04	75.0	193743	0.66	6556
Other organic materials	Bisphenof F type epoxy resin	9003-36-5	2.00 E-05	10.0	25832	0.09	874
Other organic materials	Bisphenof A type epoxy resin	25068-38-6	2.00 E-05	10.0	25832	0.09	874
Others	Additives	Proprietary	6.00 E-06	3.0	7750	0.03	262
Others	Curing Agent	Proprietary	4.00 E-06	2.0	5166	0.02	175
Subtotal			2.00 E-04	100.00	258324	0.87	8741

	Weight (g)	Percentage (%)	PPM
Package Totals	**2.96 E-02**	100.00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge.

ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

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